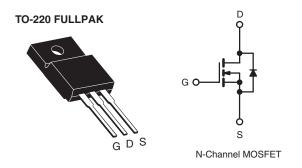


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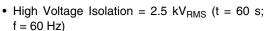
## **Power MOSFET**

PRODUCT SUMMARY				
V <sub>DS</sub> (V)	60			
$R_{DS(on)}\left(\Omega\right)$	$V_{GS} = 5 V$	0.028		
Q <sub>g</sub> (Max.) (nC)	66			
Q <sub>gs</sub> (nC)	12			
Q <sub>gd</sub> (nC)	43			
Configuration	Single			



### **FEATURES**

· Isolated Package





- Sink to Lead Creepage Distance = 4.8 mm
- · Logic-Level Gate Drive
- R<sub>DS(on)</sub> Specified at V<sub>GS</sub> = 4 V and 5 V
- · Fast Switching
- · Ease of Paralleling
- · Lead (Pb)-free

### **DESCRIPTION**

Third generation Power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220 FULLPAK eliminates the need for additional insulating hardware in commercial-industrial applications. The molding compound used provides a high isolation capability and a low thermal resistance between the tab and external heatsink. This isolation is equivalent to using a 100 micron mica barrier with standard TO-220 product. The FULLPAK is mounted to a heatsink using a single clip or by a single screw fixing.

ORDERING INFORMATION				
Package	TO-220 FULLPAK			
Lead (Pb)-free	IRLIZ44GPbF			
	SiHLIZ44G-E3			

PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			$V_{DS}$	60	V	
Gate-Source Voltage			$V_{GS}$	± 10		
Continuous Drain Current	V <sub>GS</sub> at 5 V	T <sub>C</sub> = 25 °C	- I <sub>D</sub>	30	A	
	V <sub>GS</sub> at 5 V	T <sub>C</sub> = 100 °C		21		
Pulsed Drain Current <sup>a</sup>			I <sub>DM</sub>	120	]	
Linear Derating Factor				0.32	W/°C	
Single Pulse Avalanche Energy <sup>b</sup>			E <sub>AS</sub>	400	mJ	
Maximum Power Dissipation	T <sub>C</sub> = 25 °C		$P_{D}$	48	W	
Peak Diode Recovery dV/dtc			dV/dt	4.5	V/ns	
Operating Junction and Storage Temperature Range			T <sub>J</sub> , T <sub>stg</sub>	- 55 to + 175	°C	
Soldering Recommendations (Peak Temperature)	for 10 s		,	300 <sup>d</sup>		
Mounting Torque	6-32 or M3 screw			10	lbf ⋅ in	
				1.1	N⋅m	

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b.  $V_{DD} = 25 \text{ V}$ , starting  $T_J = 25 \,^{\circ}\text{C}$ ,  $L = 518 \,\mu\text{H}$ ,  $R_G = 25 \,\Omega$ ,  $I_{AS} = 30 \,\text{A}$  (see fig. 12c).
- c.  $I_{SD} \le 51$  A,  $dI/dt \le 250$  A/ $\mu$ s,  $V_{DD} \le V_{DS}$ ,  $T_J \le 175$  °C.
- d. 1.6 mm from case.

# IRLIZ44G, SiHLIZ44G

# Vishay Siliconix



THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum Junction-to-Ambient	R <sub>thJA</sub>	-	65	°C/W	
Maximum Junction-to-Case (Drain)	R <sub>thJC</sub>	-	3.1	C/VV	

PARAMETER	SYMBOL	TES	MIN.	TYP.	MAX.	UNIT	
Static					•		,
Drain-Source Breakdown Voltage	$V_{DS}$	V <sub>GS</sub> =	60	-	-	٧	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	-	0.070	-	V/°C	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA		1.0	-	2.0	V
Gate-Source Leakage	I <sub>GSS</sub>	,	V <sub>GS</sub> = ± 10 V		-	± 100	nA
Zava Cata Valtaga Dvain Curvent	1	V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V		-	-	25	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 48 V,	V <sub>DS</sub> = 48 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 150 °C			250	μΑ
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 5.0 V	I <sub>D</sub> = 18 A <sup>b</sup>	-	-	0.028	Ω
		V <sub>GS</sub> = 4.0 V	I <sub>D</sub> = 15 A <sup>b</sup>	-	-	0.039	
Forward Transconductance	9 <sub>fs</sub>	V <sub>DS</sub> = 25 V, I <sub>D</sub> = 18 A <sup>b</sup>		22	-	-	S
Dynamic							
Input Capacitance	C <sub>iss</sub>	$V_{GS} = 0 \text{ V},$ $V_{DS} = 25 \text{ V},$ $f = 1.0 \text{ MHz}, \text{ see fig. 5}$ $f = 1.0 \text{ MHz}$		-	3300	-	pF
Output Capacitance	C <sub>oss</sub>			-	1200	-	
Reverse Transfer Capacitance	C <sub>rss</sub>			-	200	-	
Drain to Sink Capacitance	С			-	12	-	
Total Gate Charge	Qg			-	-	66	nC
Gate-Source Charge	$Q_{gs}$	V <sub>GS</sub> = 5.0 V	$I_D = 51 \text{ A}, V_{DS} = 48 \text{ V},$ see fig. 6 and 13 <sup>b</sup>	-	-	12	
Gate-Drain Charge	$Q_{gd}$		See lig. 6 and 16	-	-	43	
Turn-On Delay Time	t <sub>d(on)</sub>	$V_{DD} = 30 \text{ V}, I_{D} = 51 \text{ A},$ $R_{G} = 4.6 \ \Omega, R_{D} = 0.56 \ \Omega,$ see fig. $10^{b}$		-	17	-	- ns
Rise Time	t <sub>r</sub>			-	230	-	
Turn-Off Delay Time	t <sub>d(off)</sub>			-	42	-	
Fall Time	t <sub>f</sub>			-	110	-	
Internal Drain Inductance	L <sub>D</sub>	Between lead, 6 mm (0.25") from package and center of die contact		-	4.5	-	- nH
Internal Source Inductance	L <sub>S</sub>			-	7.5	-	
Drain-Source Body Diode Characteristic	cs	-			ŧ.	ļ.	Į.
Continuous Source-Drain Diode Current	I <sub>S</sub>	MOSFET symbol showing the integral reverse p - n junction diode		-	-	30	А
Pulsed Diode Forward Current <sup>a</sup>	I <sub>SM</sub>			-	-	120	
Body Diode Voltage	$V_{SD}$	$T_J = 25$ °C, $I_S = 30$ A, $V_{GS} = 0$ V <sup>b</sup>		-	-	2.5	V
Body Diode Reverse Recovery Time	t <sub>rr</sub>	T <sub>J</sub> = 25 °C, I <sub>F</sub> = 51 A, dl/dt = 100 A/μs <sup>b</sup>		-	90	180	ns
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>			-	0.65	1.3	μC
Forward Turn-On Time	t <sub>on</sub>	Intrinsic tu	-on is don	ninated by	L <sub>S</sub> and I	_D)	

### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Pulse width  $\leq 300~\mu s;$  duty cycle  $\leq 2~\%.$



### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

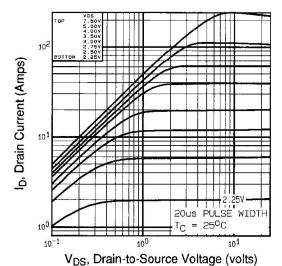


Fig. 1 - Typical Output Characteristics, T<sub>C</sub> = 25 °C

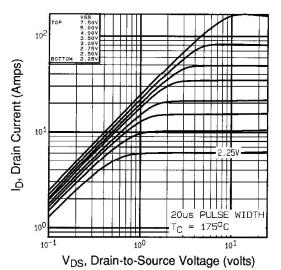


Fig. 2 - Typical Output Characteristics, T<sub>C</sub> = 175 °C

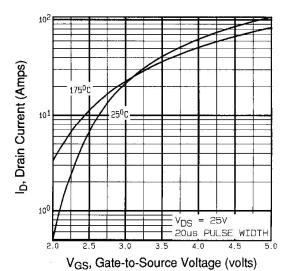


Fig. 3 - Typical Transfer Characteristics

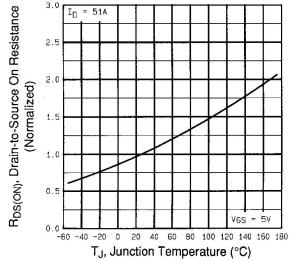


Fig. 4 - Normalized On-Resistance vs. Temperature

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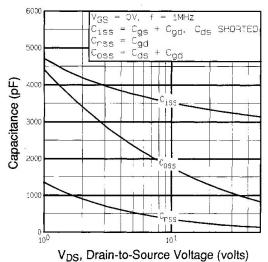
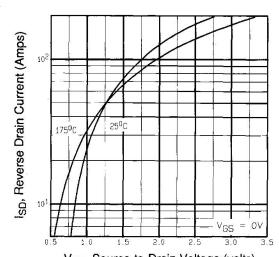


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage



V<sub>SD</sub>, Source-to-Drain Voltage (volts)

Fig. 7 - Typical Source-Drain Diode Forward Voltage

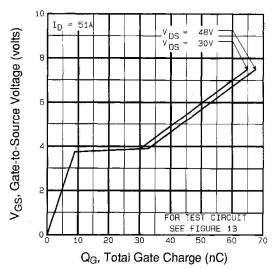


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

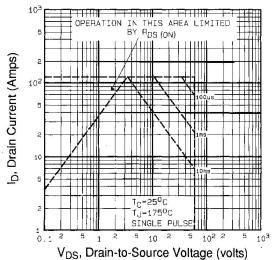


Fig. 8 - Maximum Safe Operating Area



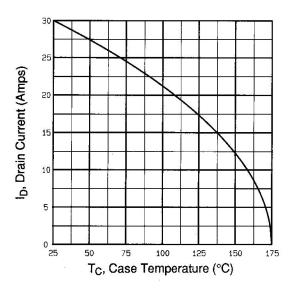


Fig. 9 - Maximum Drain Current vs. Case Temperature

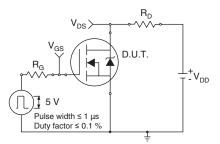


Fig. 10a - Switching Time Test Circuit

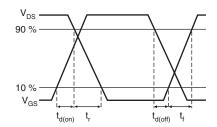


Fig. 10b - Switching Time Waveforms

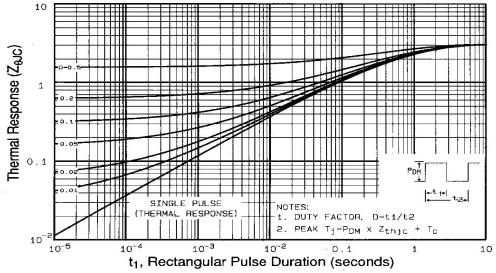


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

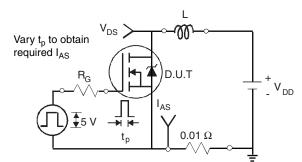


Fig. 12a - Unclamped Inductive Test Circuit

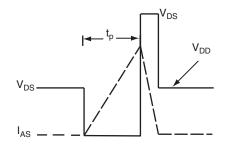


Fig. 12b - Unclamped Inductive Waveforms

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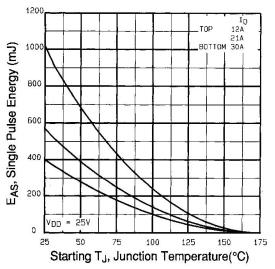


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

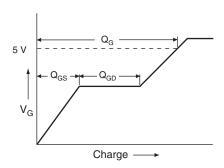


Fig. 13a - Basic Gate Charge Waveform

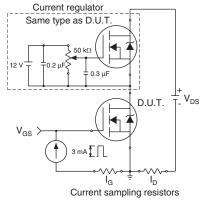
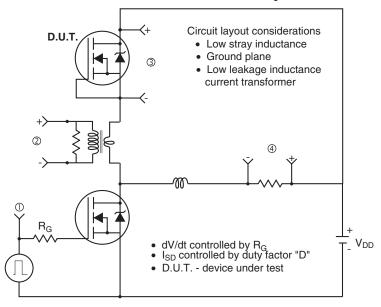
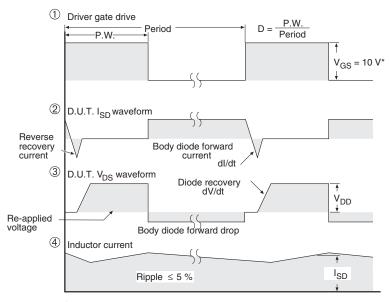


Fig. 13b - Gate Charge Test Circuit



## Peak Diode Recovery dV/dt Test Circuit





\*  $V_{GS} = 5 V$  for logic level and 3 V drive devices

Fig.14 - For N-Channel

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